

Multilayer Power Inductor

CIG21F Series (2012/ EIA 0805)

APPLICATION

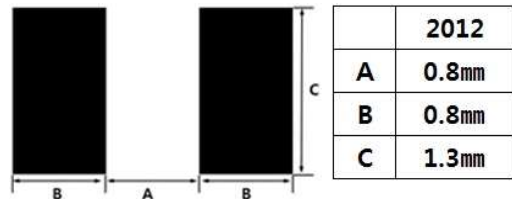
Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

FEATURES

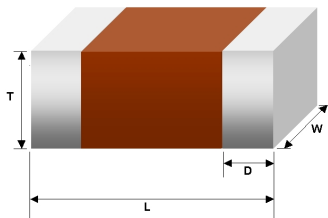
- Much lower Profile than any other series (0.5mm max)
- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability



RECOMMENDED LAND PATTERN



DIMENSION



TYPE	Dimension [mm]			
	L	W	T	D
21	2.0±0.1	1.25±0.1	0.5max	0.5+0.2 -0.3

DESCRIPTION

Part no.	Size (inch/mm)	Inductance (uH)@1MHz	DC Resistance(Ω)	Rated Current (A) Max.
CIG21FR47MNC	0805/2012	0.47 ±20 %	0.12 ±25 %	1.10
CIG21F1R0MNC	0805/2012	1.0 ±20 %	0.19 ±25 %	0.80
CIG21F1R5MNC	0805/2012	1.5 ±20 %	0.25 ±25 %	0.70
CIG21F2R2MNC	0805/2012	2.2 ±20 %	0.34 ±25 %	0.60

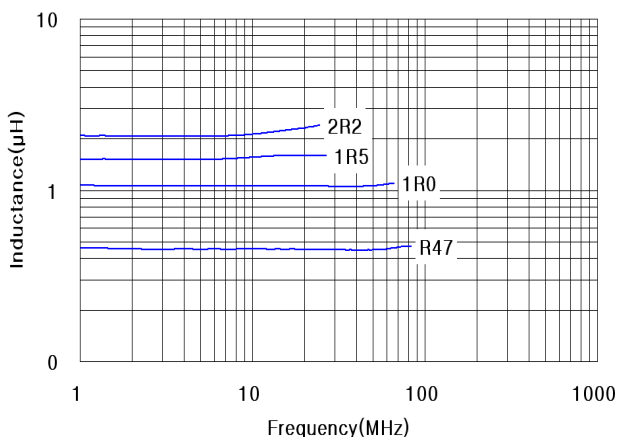
※Rated Current: DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※Operating temperature range: -40 to +125℃ (Including self-temperature rise)

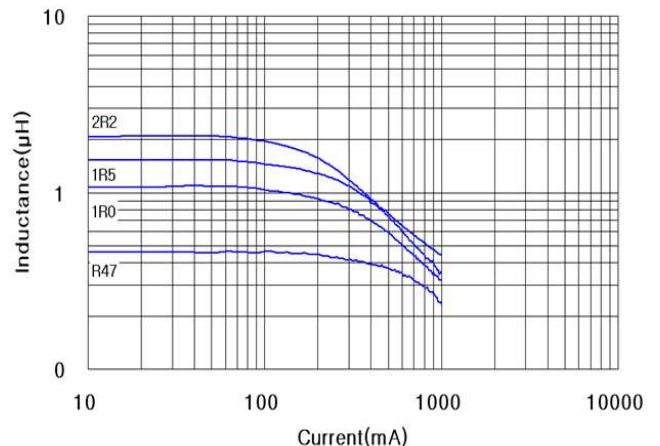
※Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



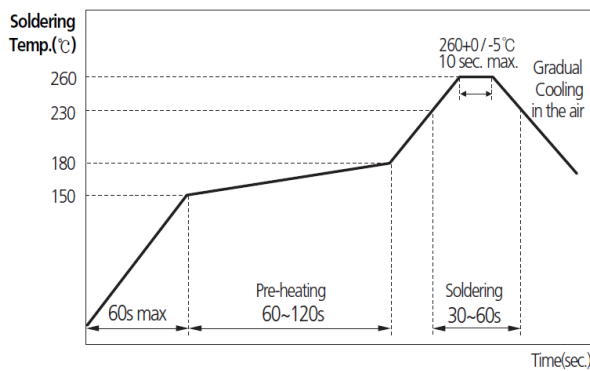
PRODUCT IDENTIFICATION

CI G 21 F 1R0 M N C
(1) (2) (3) (4) (5) (6) (7) (8)

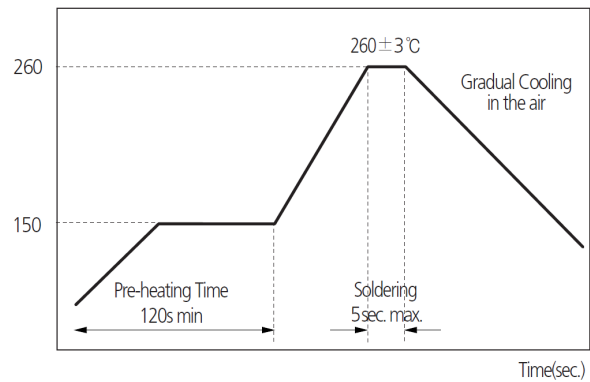
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (F:Low Profile)
- (5) Inductance (R47:0.47uH, 1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Card Board Taping	4,000

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.

单击下面可查看定价，库存，交付和生命周期等信息

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